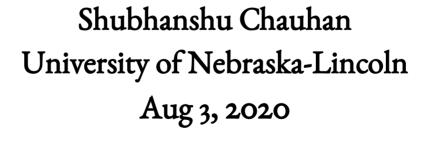
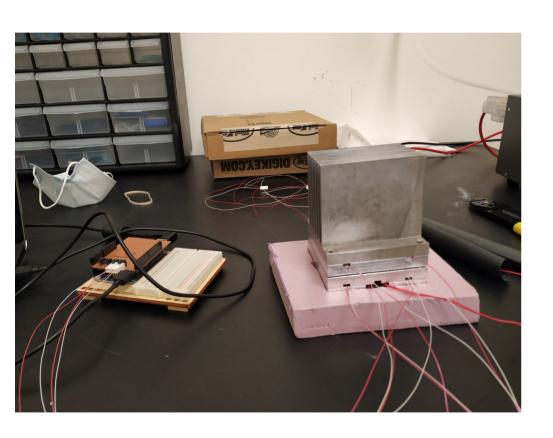
# THERMAL TESTS OF ETL MODULE COMPONENTS



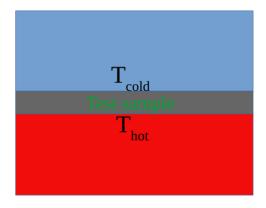




# THE SETUP



#### **Side view of the setup:**



Thermal Conductivity:

$$K = P*L/A(T_{hot}-T_{cold})$$

P: Power (heat per unit time)

L: Thinkness of the sample

A: Area of the sample

### THERMISTOR TOLERANCE: BOILING WATER TEST



- Submerged the thermistors in distilled boiling water.
- Took measurement of the temperature every 2 mins using multiple sensors.
- The boiling point at our height: 98.7 C.

Boiling point measurement: 98.62 +- 0.52 C

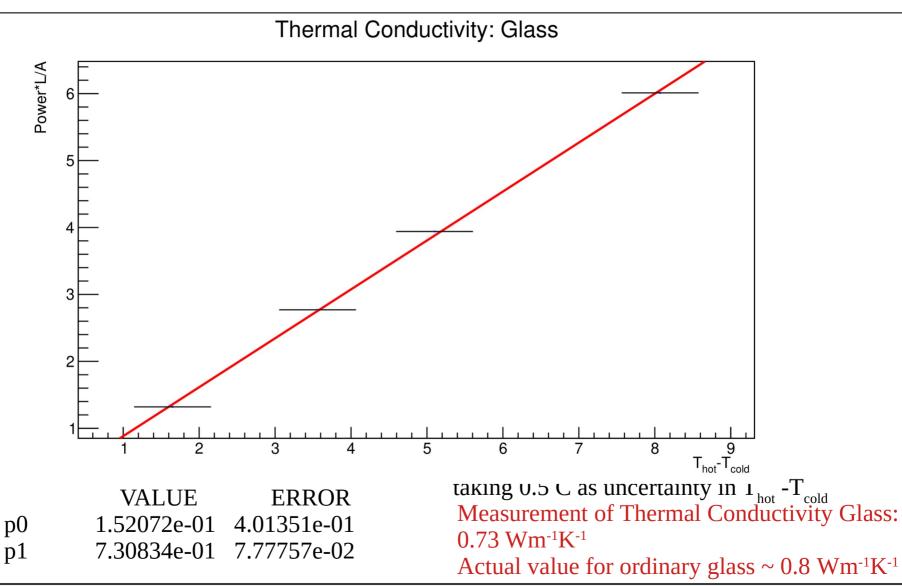
#### THERMISTOR TOLERANCE: ICE BATH TEST



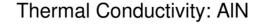
- Submerged the thermistors in ice bath of distilled water.
- Took measurement of the temperature every 2 mins using multiple sensors.
- The freezing point at our height: ~0 C.

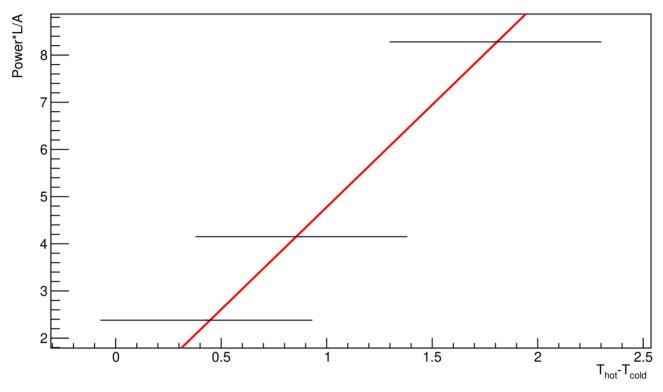
Freezing point measurement: 0.34 +- 0.19 C

# THERMAL CONDUCTIVITY: GLASS



# THERMAL CONDUCTIVITY: ALN





p0 p1 **VALUE** 

**ERROR** 4.39744e-01 2.59623e+00 4.33785e+00 2.19464e+00 taking 0.5 C as uncertainty in  $T_{hot}$  - $T_{cold}$  Measurement of Thermal Conductivity AlN: 4.3 Wm<sup>-1</sup>K<sup>-1</sup> Actual value for AlN ceremic ~ 80-140 Wm<sup>-1</sup>K<sup>-1</sup>

## LOOKING FORWARD

- Current setup might not work for the high thermally conductive materials such as AlN.
- Purdue group has a slightly different more sophisticated setup that works for wide range of materials. here